Datacon 2200 evo\textsuperscript{plus}  

Innovative Solution for Innovative Products  

The Datacon 2200 evo\textsuperscript{plus} die bonder for Multi Module Attach assembles all kinds of technologies on a tried-and-tested platform, enhanced with key features for higher bonding accuracy and lower cost-of-ownership.

Besides unbeaten flexibility and full customization possibilities, this evolutionary machine offers higher accuracy with long-term stability using a new camera system and thermal compensation algorithm, higher speed through a new image processing unit, and improved cleanroom capabilities.

Datacon 2200 evo goes PLUS!  

Enhancements  
- PLUS Accuracy  
- PLUS Productivity  
- PLUS Flexibility

Features  
- Multi-Chip Capability  
- Flexibility for Customizing  
- Open Platform Architecture

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Integrated Dispenser
- Pressure/time (Musashi®), Auger, Jetter types available
- Epoxy stamping option
- Filled and unfilled epoxy, wide viscosity range
- Small footprint, low cost-of-ownership

Vision Alignment
- New high-speed image processing unit
- Full alignment & Bad mark search
- Pre-defined fiducial geometry & customized teaching

Automatic Wafer and Tool Changer
- Fully Automatic cycle for Multi-Chip production
- Up to 7 Pick & Place tools (optionally 14), 5 eject tools
- Stamping tools and calibration tools possible

Pick & Place Head
- Die Attach, Flip Chip and Multi-Chip in one machine
- Die pick from: wafer, waffle pack, Gel-Pak®, feeder
- Die place to: substrate, boat, carrier, PCB, leadframe, wafer
- Hot and cold processes supported: epoxy, soldering, thermo-compression, eutectic

Performance
- X/Y placement accuracy: ± 7 μm @ 3s
- Theta placement accuracy: ± 0.15° @ 3s

Footprint
- L x D x H: 1160 mm x 1225 mm x 1800 mm
- Statistics
- Uptime > 98 %
- Yield > 99.95 %

Features
- Die attach: up to 7,000 UPH/module
- Flip Chip:
  - with dipping up to 2,500 UPH/module
  - without dipping up to 3,200 UPH/module
- Bond Heads
  - Standard bond head 0° - 360° rotation
  - Heated bond head (optional)
- Chip Trays
  - Waffle pack / Gel-Pak® 2” x 2” and 4” x 4”
  - JEDEC tray on request
- Substrates and Carriers
- FR4, ceramic, BGA, flex, boat, lead frame, waffle pack
- Gel-Pak®, JEDEC tray, odd-shape substrates
- Substrate working range:
  13” x 8” (325 mm x 200 mm)

Options
- Hardware: Open platform architecture for full customization
- Software: Single component tracking, CAD download, wafer mapping, substrate mapping, barcode scanner, datamatrix recognition and more.

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